

Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	B320AE	B330AE	B340AE	B345AE	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	VRRM VRWM VRM	20	30	40	45	V
Average Rectified Output Current	lo	3		Α		
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	IFSM	80			А	

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 6)	Reja	60	°C/W
Typical Thermal Resistance Junction to Case (Note 6)	Rejc	30	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Min	Тур	Max	Unit	Test Condition
Forward Voltage Drop	VF	_	0.45	0.50	V 1	IF = 3A, T _J = +25°C	
		_	0.40	_		IF = 3A, T _J = +125°C	
	B320AE		_	_	0.10		V _R = 20V, T _J = +25°C
Leakage Current (Note 7) B340A	B330AE		_	_	0.15		$V_R = 30V, T_J = +25^{\circ}C$
	B340AE		_	_	0.20		$V_R = 40V, T_J = +25^{\circ}C$
	B345AE		_	_	0.30		V _R = 45V, T _J = +25°C
			_	35	_		V _R = 45V, T _J = +125°C
Typical Capacitance		Ст	_	140	_	pF	$V_R = 4.0V, f = 1MHz$

Notes:

^{6.} Device mounted on FR-4 substrate, 1"*1", 2oz, single-sided, PC boards with 0.56"*0.73" copper pad.

^{7.} Short duration pulse test used to minimize self-heating effect.



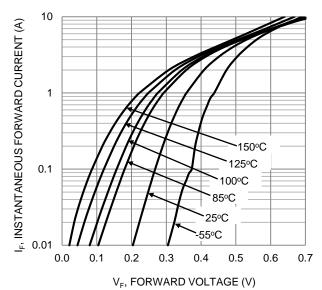


Figure 1. Typical Forward Characteristics

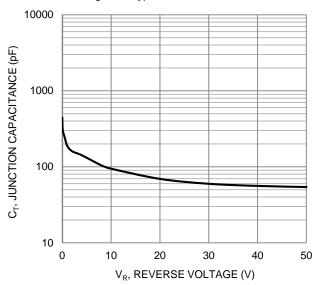


Figure 3. Typical Junction Capacitance

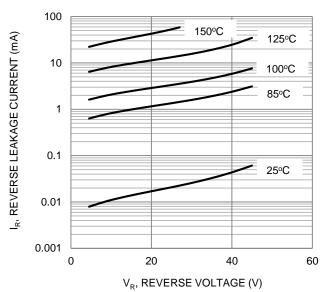


Figure 2. Typical Reverse Characteristics

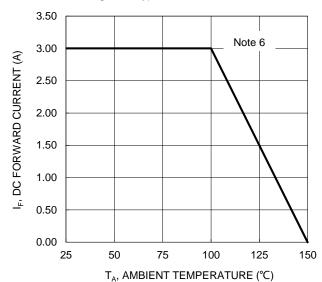


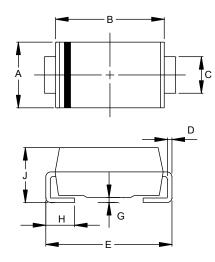
Figure 4. DC Forward Current Derating



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SMA

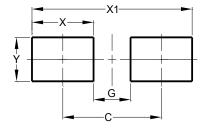


SMA					
Dim	Min	Max			
Α	2.29	2.92			
В	4.00	4.60			
С	1.27	1.63			
D	0.15	0.31			
Е	4.80	5.59			
G	0.05	0.20			
Н	0.76	1.52			
J	1.96	2.40			
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SMA



Dimensions	Value (in mm)
С	4.00
G	1.50
Х	2.50
X1	6.50
Υ	1.70



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5 of 5

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